# Single 2-Input NOR Gate/ CMOS Logic Level Shifter

# with LSTTL-Compatible Inputs

The MC74VHC1GT02 is a single gate 2-input NOR fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer output which provides high noise immunity and stable output.

The device input is compatible with TTL-type input thresholds and the output has a full 5.0 V CMOS level output swing. The input protection circuitry on this device allows overvoltage tolerance on the input, allowing the device to be used as a logic-level translator from 3.0 V CMOS logic to 5.0 V CMOS Logic or from 1.8 V CMOS logic to 3.0 V CMOS Logic while operating at the high-voltage power supply.

The MC74VHC1GT02 input structure provides protection when voltages up to 7 V are applied, regardless of the supply voltage. This allows the MC74VHC1GT02 to be used to interface 5 V circuits to 3 V circuits. The output structures also provide protection when  $V_{CC}=0$  V. These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

- High Speed:  $t_{PD} = 4.7 \text{ ns (Typ)}$  at  $V_{CC} = 5 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \mu A$  (Max) at  $T_A = 25^{\circ}C$
- TTL-Compatible Inputs: V<sub>II</sub> = 0.8 V; V<sub>IH</sub> = 2.0 V
- CMOS–Compatible Outputs: V<sub>OH</sub> > 0.8 V<sub>CC</sub>; V<sub>OL</sub> < 0.1 V<sub>CC</sub> @Load
- Power Down Protection Provided on Inputs and Outputs
- Balanced Propagation Delays
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FETs = 65

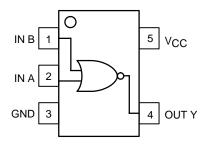


Figure 1. Pinout

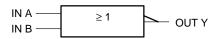


Figure 2. Logic Symbol



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SC70-5/SC-88A/SOT-353 DF SUFFIX CASE 419A



MARKING



SOT23-5/TSOP-5/SC59-5 DT SUFFIX CASE 483



d = Date Code

PIN ASSIGNMENT							
1	IN B						
2	IN A						
3	GND						
4	OUT Y						
5	Vcc						

#### **FUNCTION TABLE**

Inp	uts	Output
Α	В	Υ
L	L	Н
L	Н	L
Н	L	L
Н	Н	L

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Charact	eristics	Value	Unit
VCC	DC Supply Voltage		-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5 to +7.0	V
VOUT	DC Output Voltage	$V_{CC} = 0$ High or Low State	−0.5 to 7.0 −0.5 to V <sub>CC</sub> + 0.5	V
lıK	Input Diode Current		-20	mA
lok	Output Diode Current	V <sub>OUT</sub> < GND; V <sub>OUT</sub> > V <sub>CC</sub>	+20	mA
lout	DC Output Current, per Pin		+25	mA
Icc	DC Supply Current, V <sub>CC</sub> and GND		+50	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case fo	r 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+ 150	°C
$\theta$ JA	Thermal Resistance	SC70-5/SC-88A/SOT-353 (Note 1) SOT23-5/TSOP-5/SC59-5	350 230	°C/W
PD	Power Dissipation in Still Air at 85°C	SC70-5/SC-88A/SOT-353 SOT23-5/TSOP-5/SC59-5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
VESD	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
ILATCH-UP	Latch-Up Performance Above V	CC and Below GND at 125°C (Note 5)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- Tested to EIA/JESD78.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit	
VCC	DC Supply Voltage		3.0	5.5	V
VIN	DC Input Voltage		0.0	5.5	V
VOUT	DC Output Voltage High or Lo	V <sub>CC</sub> = 0 ow State	0.0 0.0	5.5 VCC	V
TA	Operating Temperature Range		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $V_{CC} = 3.3 \text{ V}_{CC} = 5.0 \text{ V}$	′ ± 0.3 V ′ ± 0.5 V	0 0	100 20	ns/V

# DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

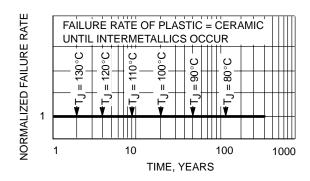


Figure 3. Failure Rate vs. Time Junction Temperature

#### DC ELECTRICAL CHARACTERISTICS

			VCC	T	A = 25°	2	T <sub>A</sub> ≤	85°C	-55 ≤ T <sub>A</sub> ≤ 125°C		
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
VIH	Minimum High-Level Input Voltage		3.0 4.5 5.5	1.4 2.0 2.0			1.4 2.0 2.0		1.4 2.0 2.0		V
V <sub>IL</sub>	Maximum Low-Level Input Voltage		3.0 4.5 5.5			0.53 0.8 0.8		0.53 0.8 0.8		0.53 0.8 0.8	V
VOH	Minimum High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50 \mu A$	3.0 4.5	2.9 4.4	3.0 4.5		2.9 4.4		2.9 4.4		V
	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
V <sub>OL</sub>	Maximum Low–Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50  \mu\text{A}$	3.0 4.5		0.0 0.0	0.1 0.1		0.1 0.1		0.1 0.1	V
	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	V
IN	Maximum Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μΑ
ICC	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1.0		20		40	μΑ
ICCT	Quiescent Supply Current	Per Input: V <sub>IN</sub> = 3.4 V Other Input: V <sub>CC</sub> or GND	5.5			1.35		1.50		1.65	mA
loff	Power Off Output Leakage Current	V <sub>OUT</sub> = 5.5 V	0.0			0.5		5.0		10	μА

#### AC ELECTRICAL CHARACTERISTICS Input $t_{\Gamma} = t_{f} = 3.0 \text{ ns}$

				T <sub>A</sub> = 25°C		<b>T</b> <sub>A</sub> ≤ 85°C		$-55 \le T_{\mbox{\scriptsize A}} \le 125^{\circ}\mbox{\scriptsize C}$			
Symbol	Parameter	Test Condit	ions	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay,	$V_{CC} = 3.3 \pm 0.3 \text{ V}$	C <sub>L</sub> = 15 pF C <sub>L</sub> = 50 pF		4.5 5.8	10.0 13.5		11.0 15.0		13.0 17.5	ns
	Input A or B to Y	$V_{CC} = 5.0 \pm 0.5 \text{ V}$	C <sub>L</sub> = 15 pF C <sub>L</sub> = 50 pF		3.0 3.8	6.7 7.7		7.5 8.5		8.5 9.5	
C <sub>IN</sub>	Maximum Input Capacitance				5.5	10		10		10	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (Note 6)	11	pF

<sup>6.</sup> CpD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$ . CpD is used to determine the no–load dynamic power consumption;  $P_{D} = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$ .

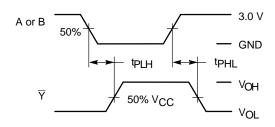
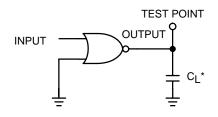


Figure 4. Switching Waveforms



\*Includes all probe and jig capacitance

Figure 5. Test Circuit

#### **DEVICE ORDERING INFORMATION**

			Device Nome	Package				
Device Order Number	Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Type (Name/SOT#/ Common Name)	Tape and Reel Size
MC74VHC1GT02DFT1	MC	74	VHC1G	T02	DF	T1	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit
MC74VHC1GT02DFT2	MC	74	VHC1G	T02	DF	T2	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit
MC74VHC1GT02DTT1	MC	74	VHC1G	T02	DT	T1	SOT23-5/TSOP-5/ SC59-5	178 mm (7 in) 3000 Unit

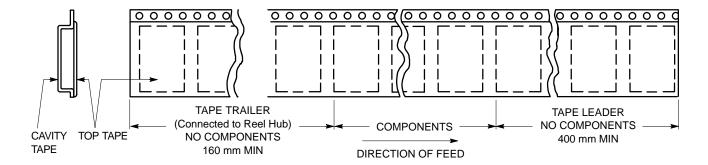


Figure 6. Tape Ends for Finished Goods

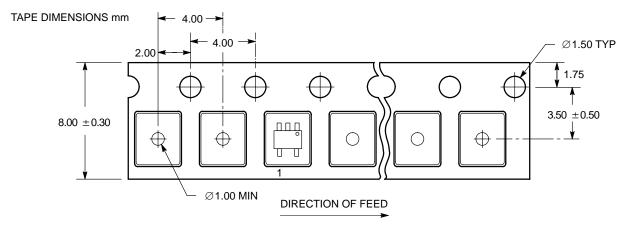


Figure 7. SC-70-5/SC-88A/SOT-353 DFT1 Reel Configuration/Orientation

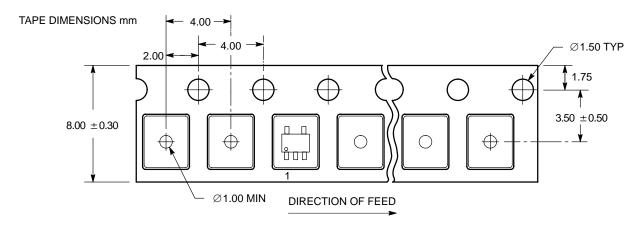


Figure 8. SC-70/SC-88A/SOT-353 DFT2 and SOT23-5/TSOP-5/SC59-5 DTT1 Reel Configuration/Orientation

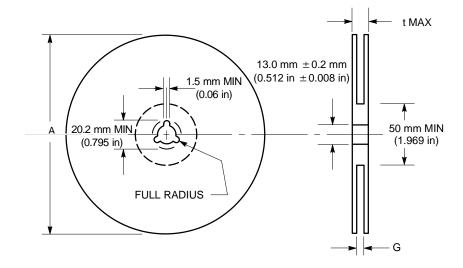


Figure 9. Reel Dimensions

#### **REEL DIMENSIONS**

Tape Size	T and R Suffix	A Max	G	t Max
8 mm	T1, T2	178 mm (7 in)	8.4 mm, + 1.5 mm, -0.0 (0.33 in + 0.059 in, -0.00)	14.4 mm (0.56 in)

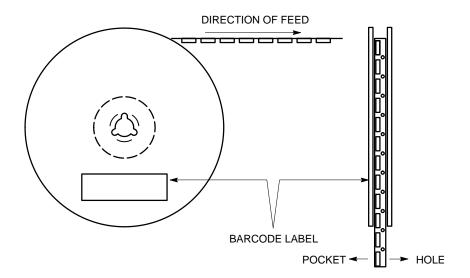
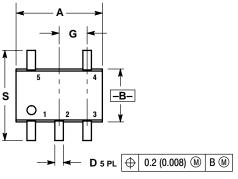


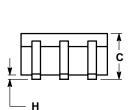
Figure 10. Reel Winding Direction

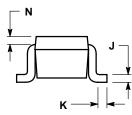
#### **PACKAGE DIMENSIONS**

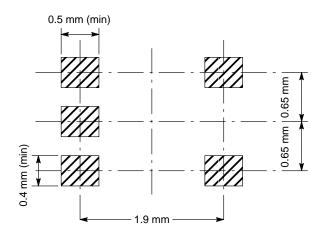
#### SC70-5/SC-88A/SOT-353 **DF SUFFIX**

5-LEAD PACKAGE CASE 419A-02 ISSUE F









#### NOTES:

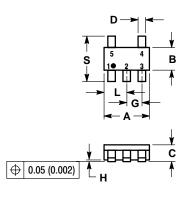
- VOIES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

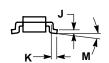
	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	REF	0.20	REF
S	0.079	0.087	2.00	2.20

#### PACKAGE DIMENSIONS

#### SOT23-5/TSOP-5/SC59-5 **DT SUFFIX**

5-LEAD PACKAGE CASE 483-01 **ISSUE B** 

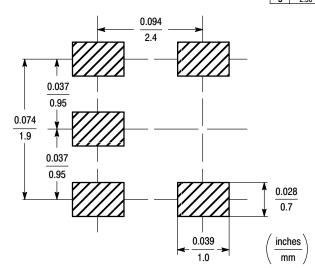




#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
M	0 °	10°	0°	10°
S	2 50	3.00	0.0985	0 1181



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